

# SOT270-1

plastic shrink dual in-line package; 42 leads (600 mil)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SDIP42
<b>Package type industry code</b>	SDIP42
<b>Package style descriptive code</b>	SDIP (shrink dual in-line package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-020
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	13-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	38.4	-	38.65	38.9	mm
E	package width	13.7	-	13.85	14	mm
A	seated height	[tbd]	-	5.08	5.08	mm
A <sub>2</sub>	package height	[tbd]	-	3.85	4	mm
n <sub>2</sub>	actual quantity of termination	-	-	42	-	



2. Package outline

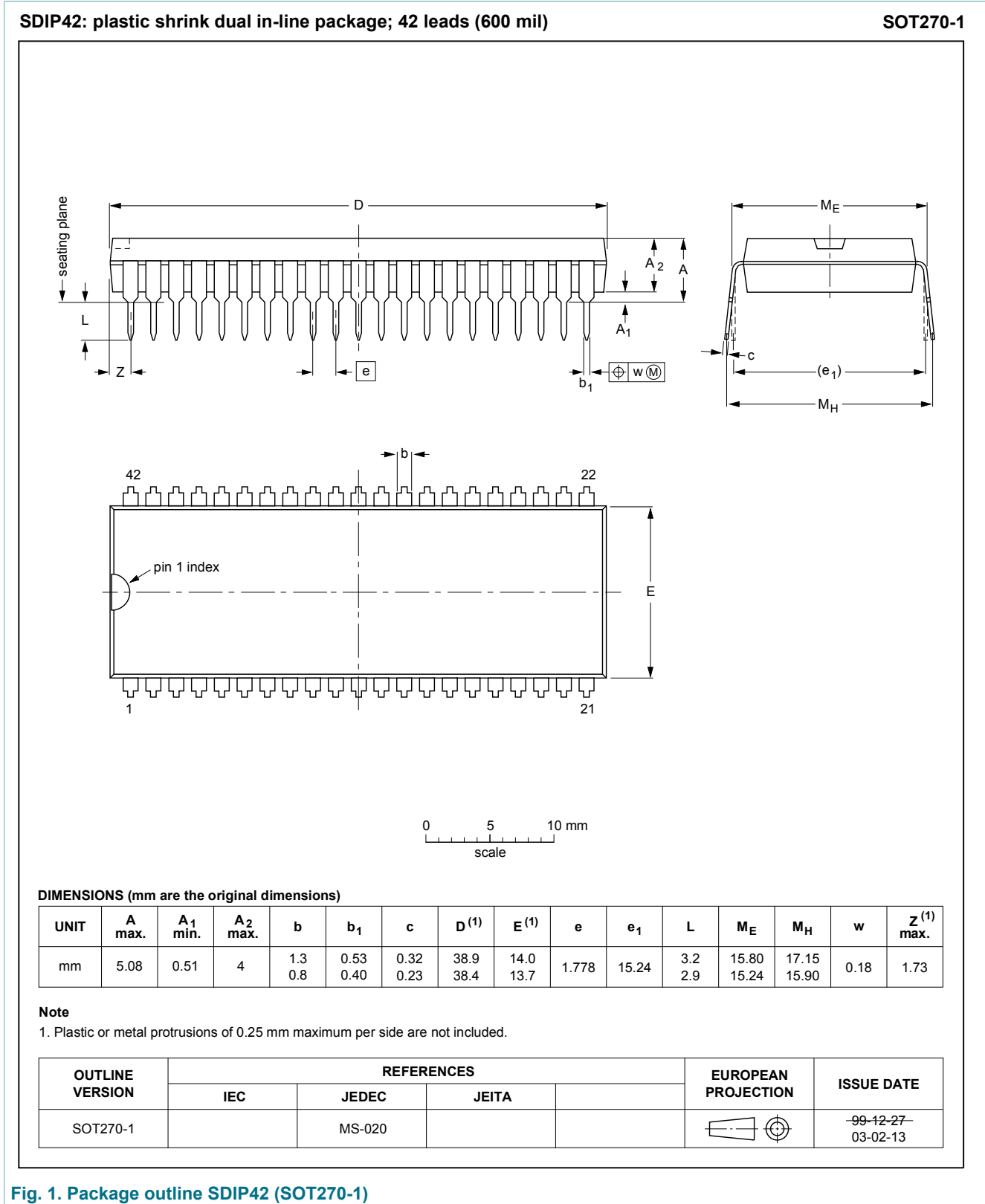


Fig. 1. Package outline SDIP42 (SOT270-1)

### 3. Legal information

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